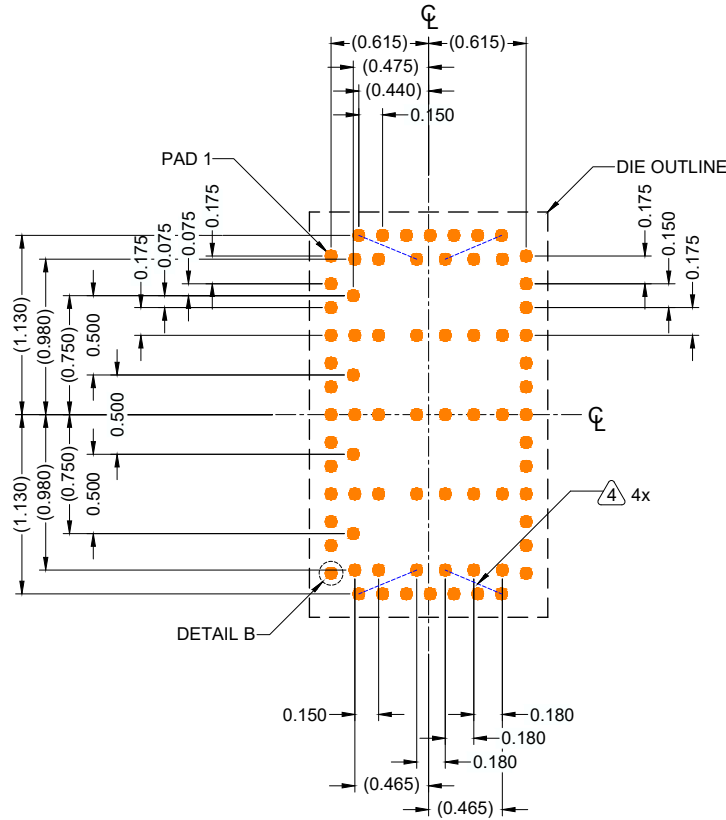
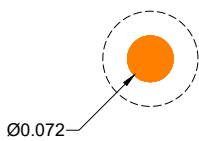


**NOTES:**

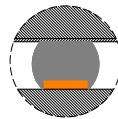
1. All dimensions are in millimeters (mm) and angles are in degrees
2. Tolerances of ±0.007mm apply to untoleranced dimensions
3. Dimensions in parenthesis ( ) are for reference only



**RECOMMENDED LAND PATTERN**  
(Substrate Top View, NSMD Design)



**DETAIL B**



**SIDE VIEW CROSS-SECTION OF BUMP ON PAD FROM DETAIL B**

**NOTES:**

1. All dimensions are in millimeters (mm) and angles are in degrees.
2. Land Pattern exhibits substrate pads for die bump connections.
3. A complete layout requires additional connections and ground patterns.
- ④ Substrate circuit requires networks for redundant die bump connections.  
Land pattern identifies pads to connect, but layout details are not shown.